IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information					
Supplier	r Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2024-05-16			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Dat	Date Version Manufacturing Site		ing Site	Weight*		UOM	Unit Type	
		NJW44H	I11G	NPN TO-3P POWER TRANS			2024-05-16	2024-05-16 KR8			5184.55		mg	Each	
Aanufa	cturing Proccess Informat	tion										,			
	Terminal Plating / Grid Array Material Terminal		erminal Base	Base Alloy J-STD-020 MSL		Rating	Peak Process Body Temperatu		mperature	ure Max Time at Peak Temper		Temperatu	re Num	ber of Reflow Cyc	eles
	Matte Tin (Sn) - annealed		CU Alloy NA		JA.		0 C		С	30 seco		second	s 3		
omments	3														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its keloardine shall encompass all such components. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall applier of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	20.45	mg	Supplier	Silicon (Si)	7440-21-3		20.45	mg
Die Attach	25.85		Supplier	Silver (Ag)	7440-22-4		0.3877	mg
			A	Lead (Pb)	7439-92-1	7a	24.1698	mg
			Supplier	Tin (Sn)	7440-31-5		1.2925	mg
Lead Frame	3425.52	mg	Supplier	Iron (Fe)	7439-89-6		3.4255	mg
			Supplier	Copper (Cu)	7440-50-8		3422.0945	mg
Mold Compound-Black	1694.84			Brominated epoxy resin	proprietary data		25.4226	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		322.0196	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		20.3381	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1327.0597	mg
Plating	14.5	mg	Supplier	Tin (Sn)	7440-31-5		14.5	mg
Wire Bond - Al	3.39	mg	Supplier	Aluminum (Al)	7429-90-5		3.39	mg